

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







CRYSTAL OSCILLATOR (Programmable) SPREAD SPECTRUM

OUTPUT: CMOS

SG-9101 series

• Frequency range : 0.67 MHz ~ 170 MHz (1 ppm Step)

• Supply voltage : 1.62 V ~ 3.63 V

 Function : Output enable (OE) or Standby (ST)

• Down or Center spread modulation

· Configurable spreading

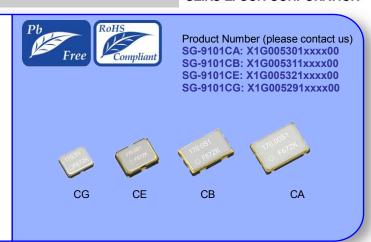
3 modulation profile (Hershey-kiss, Sine-wave, Triangle),

4 modulation frequency, 6 spread percentage

: 2.5 x 2.0, 3.2 x 2.5, 5.0 x 3.2, 7.0 x 5.0 (mm)

• PLL technology to enable short lead time

Available field oscillator programmer "SG-Writer II"



Specifications (characteristics)

Item	Item Symbo		Specifications				Condition	ons/Remarks	
Supply voltage		Vcc	1.80 \		2.50 V Typ.	3.30 V Typ.	_	_	
		VCC	1.62 V ~ 1.98 V	1.98 V ~ 2.20 V	2.20 V ~ 2.80 V	2.70 V ~ 3.63 V		<u> </u>	
Output frequence	cy range	fo		0.67 MHz	~ 170 MHz				
Storage temper	ature	T_stg			+125 °C		Storage as single produc	t.	
Operating temp	erature	T use			~ +85 °C		_		
Frequency toler		f tol			× 10 ⁻⁶		Average frequency of 1s gate time.		
requericy toler	ance	1_101	3.4 mA Max.	3.5 mA Max.	3.6 mA Max.	3.7 mA Max.	T use = +105 °C	gate time.	
			2.9 m		3.0 mA Typ.	3.2 mA Typ.	T use = +25 °C	o load, f ₀ = 20 MHz	
Current consum	nption	Icc	5.7 mA Max.	6.0 mA Max.	6.9 mA Max.	8.3 mA Max.	T_use = +105 °C		
			4.9 m		5.9 mA Typ.	7.0 mA Typ.	T use = +25 °C	o load, f _O = 170 MHz	
Output disable	current	I dis	3.4 mA Max.	3.4 mA Max.	3.5 mA Max.	3.7 mA Max.	OE = GND, f _O = 170 MHz	,	
Output disable t	current	1_013	0.9 µA Max.	1.0 µA Max.	1.5 µA Max.	2.5 µA Max.	T use = +105 °C		
Standby current	t	I_std	0.3 μA Typ.	0.4 μA Typ.	0.5 μA Typ.	1.1 μA Typ.	T use = +25 °C	Ī = GND	
Symmetry		SYM	о.о р. стур.		~ 55 %		50 % V _{CC} Level		
							I _{OH} /I _{OL} Conditions	[mA]	
		Vон					Rise/Fall time	Vcc *A *B *C *D	
			90 % V _{CC} Min.			$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			
Output voltage (DC characteris	tion)								
(DC Characteris	ilics)								
		V _{OL}	10 % V _{CC} Max.			Slow	loн -1.0 -1.5 -2.0 -2.5 lol 1.0 1.5 2.0 2.5		
						*A : 1.62 V ~ 1.98 V, *B : 1.98 V ~ 2.20			
						*C : 2.20 V ~ 2.80 V, *D : 2.70 V ~ 3.63 \			
Output load cor	ndition	L_CMOS	15 pF Max.				-		
Input voltage		V_{IH}	70 % V _{CC} Min.		OE or ST				
Input voltage		V_{IL}		30 % \	/cc Max.		OE or ST		
	D - f II			3.0	ns Max.		f _O > 40 MHz		
Rise and Fall	Default			6.0 ns Max.			f _O ≤ 40 MHz	20 % - 80 % Vcc	
time	Fast	tr/tf	3.0 ns Max.		f _O = 0.67 MHz ~ 170 MHz				
	Slow		10.0 ns Max.			f _O = 0.67 MHz ~ 20 MHz			
Disable Time		t_stp	1 μs Max.			Measured from the time OE or ST pin crosses 30 %			
Enable Time		t_sta	1 µs Max.			Measured from the time OE pin crosses 70 % V _{CC}			
Resume Time		t_res		3	ms Max.		Measured from the time ST pin crosses 70 % Vcc		
_		t_str	3 ms Max.			Measured from the time V _{CC} reaches its rated minimum value, 1.62 V			

^{*1} Frequency tolerance includes initial frequency tolerance, temperature variation, supply voltage variation, reflow drift, load drift and aging (+25 °C, 1 year).

Spread spectrum configuration

	C: Center spread	⑤Code	02	05	07	10	15	20
4	modulation	Spread percentage	±0.25 %	±0.5 %	±0.75 %	±1.0 %	±1.5 %	±2.0 %
4)	D: Down spread	⑤Code	05	10	15	20	30	40
	modulation	Spread percentage	-0.5 %	-1.0 %	-1.5 %	-2.0 %	-3.0 %	-4.0 %

Modulation frequency: 25.4 kHz (default), 6.3 kHz, 8.5 kHz, 12.7 kHz

Modulation profile: Hershey-kiss (default), Sine-wave, Triangle

Product Name

SG-9101CG 170.000000MHz C 20 P H A A A (2) Package Type CA: 7.0 mm x 5.0 mm

4567890

CB: 5.0 mm x 3.2 mm CE: 3.2 mm x 2.5 mm

CG: 2.5 mm x 2.0 mm

⑥Function	
P: Output enable	
S: Standby	

④Spread type C: Center spread

D: Down spread

	⑦Operating temperature
	G: -40 °C ~ +85 °C
	H: -40 °C ~ +105 °C
- 11	

Modulation profile
A: Hershey-kiss (default)
B: Sine-wave
C: Triangle

A: 25.4 kHz (default)		@Ris
B: 12.7 kHz		A: De
C: 8.5 kHz		B: Fa
D: 6.3 kHz	ı	C: Slo

®Rise/Fall time	
A: Default	
B: Fast	
C: Slow	

①Model, ②Package type, ③Frequency,

Spread type,
 Spread percentage code,

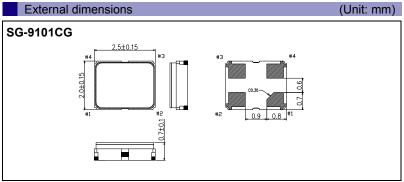
⑤Function, ⑦Operating temperature,

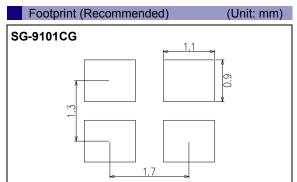
[®] Modulation frequency, 9 Modulation profile, 1 Rise/Fall time

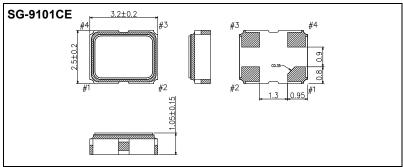


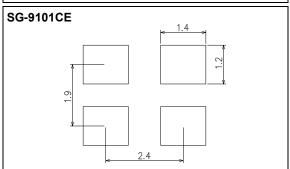
Pin description

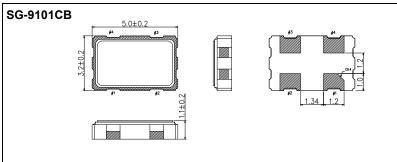
Pin	Name	I/O type	Function				
	OE	Input	Output enable	High: Specified frequency output from OUT pin			
	OL	IIIput	Output eriable	Low: Out pin is low (weak pull down), only output driver is disabled.			
1				High: Specified frequency output from OUT pin			
	ST	Input	Standby	Low: Out pin is low (weak pull down),			
				Device goes to standby mode. Supply current reduces to the least as I_std.			
2	GND	Power	Ground				
3	OUT	Output	Clock output				
4	V _{CC}	Power	Power supply				

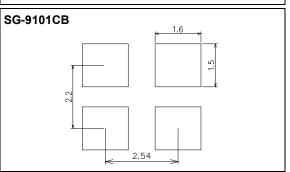


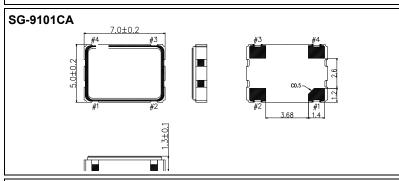


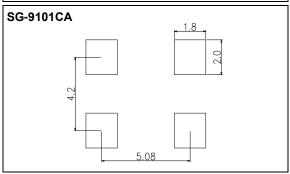








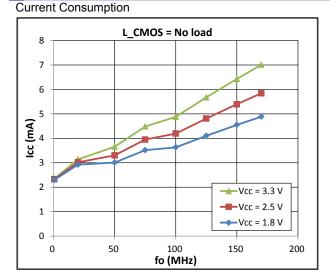


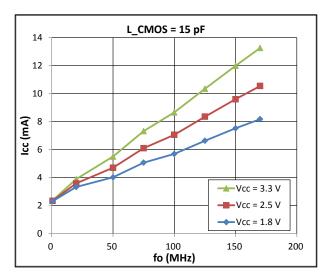


■Notes:

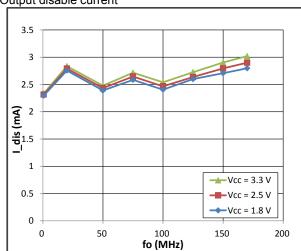
In order to achieve optimum jitter performance, the 0.1 μ F capacitor between V_{CC} and GND should be placed. It is also recommended that the capacitors are placed on the device side of the PCB, as close to the device as possible and connected together with short wiring pattern.

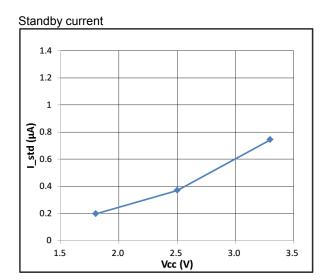
Specification Graph (Typical supplemental specification. Unless otherwise specified T_use = 25 °C, L_CMOS = 15pF)





Output disable current



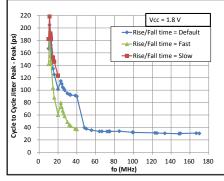


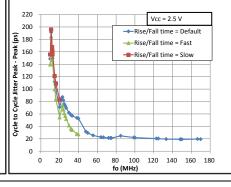
■ Notes:

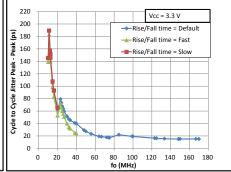
Spead percentage : $\pm 2.0 \%$, Modulation frequency : 25.4 kHz , Modulation profile : Hershey-kiss

Specification Graph (Typical supplemental specification. Unless otherwise specified T_use = 25 °C, L_CMOS = 15pF)

Cycle-to-Cycle Jitter Peak-Peak





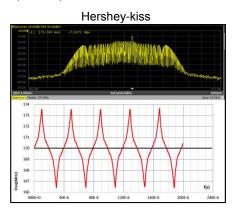


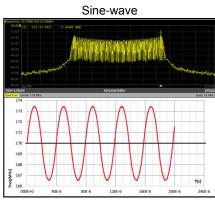
■ Notes:

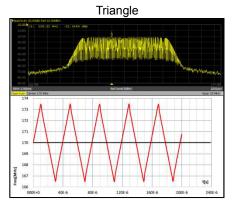
Spead percentage : $\pm 2.0~\%$, Modulation frequency : 25.4 kHz , Modulation profile : Hershey-kiss

Spread Spectrum Specification Graph

Spread Spectrum Profile fo: 170 MHz / Spread spectrum: ± 2.0 % / Modulation frequency: 25.4 kHz



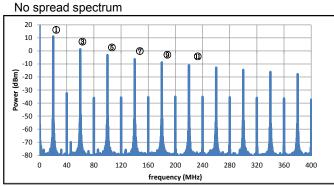


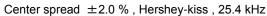


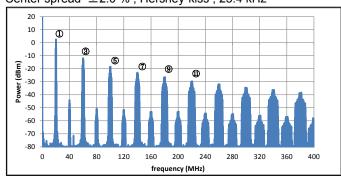
Harmonics Specification Graph

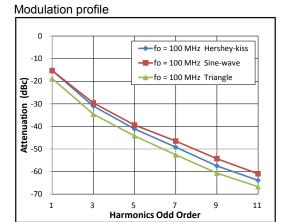
(Typical supplemental specification. Unless otherwise specified T_use = 25 °C, L_CMOS = 15pF, Vcc = 3.3 V)

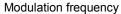
Harmonics spectrum (fo = 20 MHz)

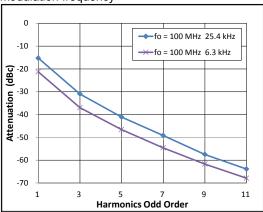


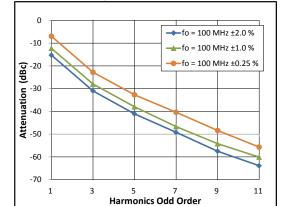




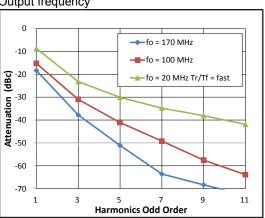










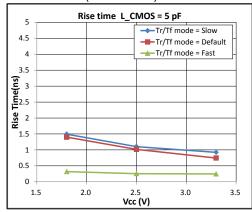


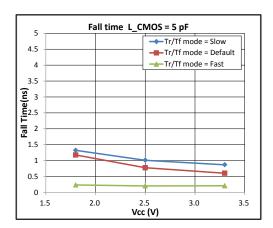
Spread percentage

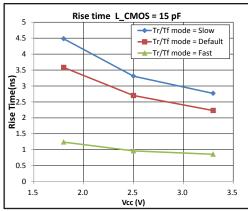
Hermonics order attenuation is normalizing to no-spread spectrum mode.

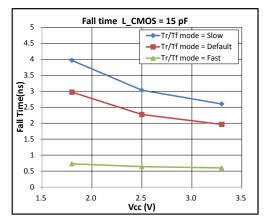
Specification Graph (Typical supplemental specification. Unless otherwise specified T_use = 25 °C, L_CMOS = 15pF)

Rise/Fall Time (fo = 20 MHz)



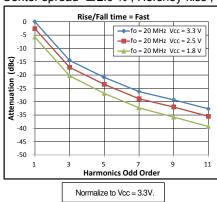


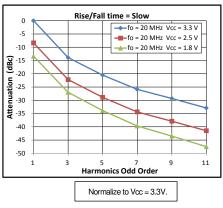


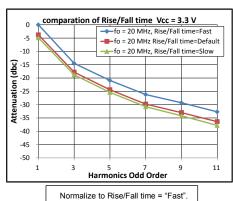


Harmonics comparison

Center spread ±2.0 %, Hershey-kiss, 25.4 kHz







■Notes:

frequency	slow	default	fast
0.67 M - 20 M	See Slow	See Default	See Fast
20 M – 40 M	-	See Default	See Fast
40 M – 170 M	-	See Fast	See Fast



Simulation Model

IBIS Model is available upon request. Please contact us.
 Information Required: Oscillator operating condition (i.e. Power Supply, Rise/Fall Time, Temperature)

ESD Rating

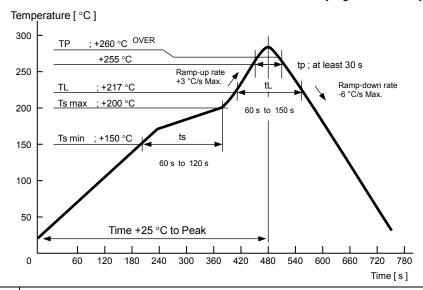
Test items	Breakdown voltage
Human Body Model (HBM)	2000V
Machine Model (MM)	250V
Charged Device Model (CDM)	750V

Device Material & Environmental Information

Model	Package	# of	Reference	Terminal	Terminal	Complies	Pb	MSL	Peak
	Dimensions	Pins	Weight	Material	Plating	With EU	Free	Rating	Temp.
			(Typ.)			RoHS			(Max)
SG-9101CG	2.5x2.0x0.7mm	4	13 mg	W	Au	Yes	Yes	1	260°C
SG-9101CE	3.2x2.5x1.0mm	4	25 mg	W	Au	Yes	Yes	1	260°C
SG-9101CB	5.0x3.2x1.1mm	4	51 mg	W	Au	Yes	Yes	1	260°C
SG-9101CA	7.0x5.0x1.3mm	4	143 mg	W	Au	Yes	Yes	1	260°C

SMD products Reflow profile(example)

The availability of the heat resistance for reflow conditions of JEDEC-STD-020D.01 is judged individually. Please inquire.





• Pb free.



- Complies with EU RoHS directive.
 - About the products without the Pb-free mark.
 Contains Pb in products exempted by EU RoHS directive.
 (Contains Pb in sealing glass, high melting temperature type solder or other.)

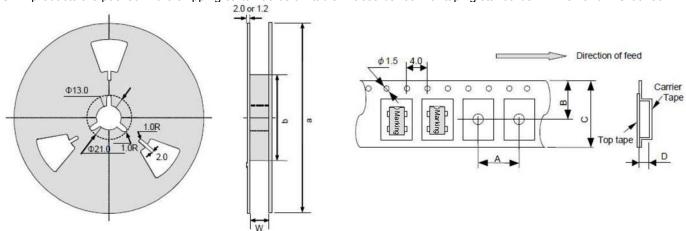


Device Marking

Model	Factory Programmed Part Marking	Field Programmable Part Marking (Blank Samples)
SG-9101CG	Frequency Product code 170.S1 OA23DK 1pin mark Lot No.	Product code S1 OA23DK 1pin mark Lot No.
SG-9101CE	Frequency 170.0S1 o A23DK 1pin mark Lot No.	Product code S1 o A23DK Lot No.
SG-9101CB	Frequency 170.0S1 o A23DK Lot No.	S1 O A23DK Lot No.
SG-9101CA	Frequency 170.00S1 o A23DK Lot No.	S1 O A23DK Lot No.

Standard Packing Specification

SMD products are packed in the shipping carton as below table in accordance with taping standards EIA-481 and IEC-60286



Standard Packing Quantity & Dimension(Unit mm)

Claired a Coloning Casaring a Emission (Cincinn)									
Model	Quantity (pcs/Reel)	Reel Dimension			Career Tape Dimension				Direction of
		а	b	W	А	В	С	D	Feed (L= Left
									Direction)
SG-9101CG	3000	Ф180	Ф60	9	4	5.25	8	1.15	L
SG-9101CE	2000	Ф180	Ф60	9	4	5.25	8	1.4	L
SG-9101CB	1000	Ф180	Ф60	13	8	7.25	12	1.4	L
SG-9101CA	1000	Ф254	Ф100	17.5	8	9.25	16	2.3	L

PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Seiko Epson, all environmental initiatives operate under the Plan-Do-Check-Action (PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard.

All of our major manufacturing and non-manufacturing sites, in Japan and overseas, completed the acquisition of ISO 14001 certification.

ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

WORKING FOR HIGH QUALITY

In order provide high quality and reliable products and services than meet customer needs,

Seiko Epson made early efforts towards obtaining ISO9000 series certification and has acquired ISO9001 for all business establishments in Japan and abroad. We have also acquired ISO/TS 16949 certification that is requested strongly by major automotive manufacturers as standard.

ISO/TS16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

Explanation of the mark that are using it for the catalog



►Pb free.



- ► Complies with EU RoHS directive.
 - *About the products without the Pb-free mark.

 Contains Pb in products exempted by EU RoHS directive.

 (Contains Pb in sealing glass, high melting temperature type solder or other.)



▶ Designed for automotive applications such as Car Multimedia, Body Electronics, Remote Keyless Entry etc.



 \blacktriangleright Designed for automotive applications related to driving safety (Engine Control Unit, Air Bag, ESC etc).

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